

ABSTRACT

A rubber composition for cleaning a mold to remove stains deposited during molding of a curing resin, in which an unvulcanized rubber comprising an ethylene-propylene rubber and a butadiene rubber in a mixing ratio of 90/10 to 50/50 is used as a base resin. The unvulcanized rubber has a 90% cure time (optimum cure point) $t_c(90)$ of from 50 to 100 seconds or from 200 to 400 seconds at a mold temperature of 175°C and, after cure, an elongation of 80% to 800%, a tensile strength of 3 to 10 MPa, and a rubber hardness (durometer A hardness) of 60 to 95. For use to molds having deep cavities for small packages, such as PDIPs and SOICs, particularly those for small packages with a small number of pins, the composition preferably comprises the unvulcanized rubber having $t_c(90)$ of 200 to 400 seconds and a release agent.